## AMENDMENT TO THE SPECIFICATION:

Please replace the title with the following amended title:

## MAGNETIC HEAD WITH MAGNETIC LAYERS OF DIFFERING WIDTHS AND THIRD POLE WITH REDUCED THICKNESS

Please replace the paragraph found at p. 1, line 28 to p. 2, line 4 with the following amended paragraph:

In order to write onto a narrow track on the recording medium, the upper pole is made very narrow and has reached submicron widths in current writing devices. To reach even smaller sized, a wider third pole (P3) layer may be added to support and aid in the fabrication of the upper pole layer. Viewed from the ABS, the third pole and upper (P2) layer together have a T-shape, with the wider third pole layer forming the crosspiece of the T. T-shaped pole piece structures are known in the art and are described, for example, in US Patent 5,238,942-5,283,942.

Please replace the paragraph found at p. 9, lines1-13 with the following amended paragraph:

A first magnetic layer 52 having the first pole 54 is deposited upon the substrate 100, numeral 202. The gap insulator layer 58 is deposited on the first magnetic layer 52, numeral 204. The second magnetic layer 60 is deposited overlying the gap insulator layer 58, numeral 206. The second magnetic layer 60 includes the second magnetic layer portion 62 having the second pole 64 thereon. The second layer insulator portion 68, and the back gap layer portion 66. The second magnetic layer 60 has a planar upper surface after deposition 206. [[the]] The inductive coil 74 and its coil insulation 78 are deposited over the second-layer insulator portion 66 of the second magnetic layer 60, numeral 208.

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numeral 208. The third magnetic layer 70, having the third pole 72 and a non-pole portion (the non-pole portion being all of the third magnetic layer 70 except for the third pole 72), is deposited over the inductive coil 74 and the remaining exposed portion of the second magnetic layer 60, numeral 210. The deposited third pole 72 contacts the previously deposited second pole 64. Figure 9 depicts the structure at this stage of the fabrication processing.